



Product Overview:

Comes with 3 ultra-efficient thermal heat pipes. Air cooling solution powered by Heat Core Touch Technology (HCTT) and equipped with high efficiency fins, TDP up to 125W. Compatible with most current motherboard designs: LGA 1150/1151/1155/1156/775 and AM4/AM3+/AM3/AM2+/AM2/ FM2/FM1.

Specifications

Model		Verkho 3 Plus
Base Material		Aluminum block with HCTT Heat Core Touch Technology
Fin Material		Aluminum
Heat pipe		6mm x 3
Dimension		125 x 78 x 134mm
TDP(Thermal Design Power)		125
Fan	Speed	1000-2000 rpm
	Connector	PWM 4-Pin
	Dimension	120 x 120 x 25mm
	Bearing Type	Hydraulic Bearing
	Started Voltage	5V
	Rated Voltage	12V
	Rated Current	0.2 A
	Power Consumption	2.4 Watts
	Air Pressure	0.78-1.24 mm-H2O
	Air Flow	29.1-55.6 CFM
	Noise	18.2-26.7 dBA
	MTBF (Mean Time Before Failure)	60000 hrs.
Socket		LGA 1150/1151/1155/1156/775 AM4/AM3+/AM3/AM2+/AM2/FM2/FM1

ALL TRADEMARKS ARE REGISTERED TO THEIR RESPECTIVE OWNERS.

Warranty

2 years

Features

- TDP (Thermal Design Power) up to 125W.
- Compact side flow air cooler for maximum compatibility.
- Heat Core Touch Technology and 3 ultra-efficient thermal heat pipes.
- Upgraded high efficiency fins for optimal thermal performance.
- Ultra-slim profile, works with most current motherboard designs: LGA 1150/1151/1155/ 1156/775 and AM4/AM3+/AM3/AM2+/AM2/FM2/FM1.

Package Information

Product Name	No. Model	EAN CODE
Verkho 3 Plus	ACTC-NA30310.01	4713105960891

Carton Size (L x W x H)	425 x 330 x 365 mm	Carton Weight
Retail Box Size (L x W x H)	135 x 104 x 175 mm	Retail Box Weight
Carton Qty	18 pcs	Pallet Qty

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